



STP16NF06L STP16NF06LFP

N-CHANNEL 60V - 0.07 Ω - 16A TO-220/TO-220FP
STripFET™ II POWER MOSFET

| TYPE | V _{DSS} | R _{DS(on)} | I _D |
|--------------|------------------|---------------------|----------------|
| STP16NF06L | 60 V | <0.09 Ω | 16 A |
| STP60NF06LFP | 60 V | <0.09 Ω | 11 A |

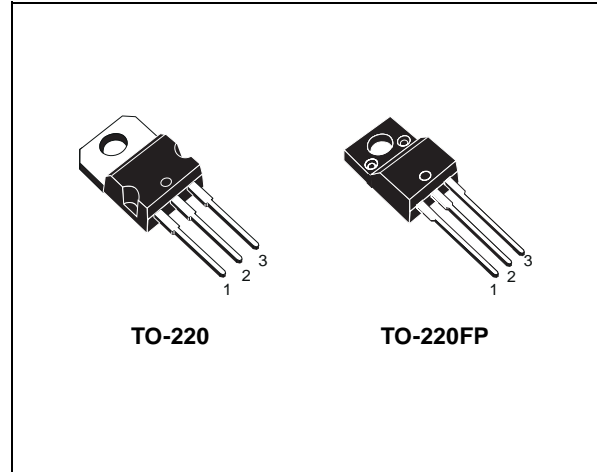
- TYPICAL R_{DS(on)} = 0.07 Ω
- EXCEPTIONAL dv/dt CAPABILITY
- LOW GATE CHARGE AT 100 °C
- LOW THRESHOLD DRIVE

DESCRIPTION

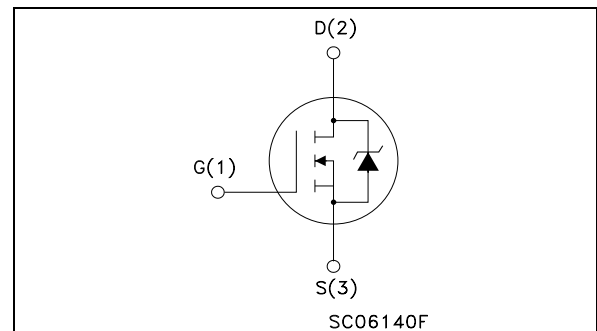
This Power MOSFET is the latest development of STMicroelectronics unique "Single Feature Size™" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps therefore a remarkable manufacturing reproducibility.

APPLICATIONS

- MOTOR CONTROL, AUDIO AMPLIFIERS
- HIGH CURRENT, HIGH SPEED SWITCHING
- SOLENOID AND RELAY DRIVERS
- DC-DC & DC-AC CONVERTERS
- AUTOMOTIVE ENVIRONMENT



INTERNAL SCHEMATIC DIAGRAM



ABSOLUTE MAXIMUM RATINGS

| Symbol | Parameter | Value | | Unit |
|---------------------|---|------------|--------------|------|
| | | STP16NF06L | STP16NF06LFP | |
| V _{DS} | Drain-source Voltage (V _{GS} = 0) | 60 | | V |
| V _{DGR} | Drain-gate Voltage (R _{GS} = 20 k Ω) | 60 | | V |
| V _{GS} | Gate- source Voltage | ± 16 | | V |
| I _D | Drain Current (continuous) at T _C = 25°C | 16 | 11(*) | A |
| I _D | Drain Current (continuous) at T _C = 100°C | 11 | 7.5(*) | A |
| I _{DM} (•) | Drain Current (pulsed) | 64 | 44(*) | A |
| P _{tot} | Total Dissipation at T _C = 25°C | 45 | 25 | W |
| | Derating Factor | 0.3 | 0.17 | W/°C |
| dv/dt (1) | Peak Diode Recovery voltage slope | 23 | | V/ns |
| E _{AS} (2) | Single Pulse Avalanche Energy | 127 | | mJ |
| V _{ISO} | Insulation Withstand Voltage (DC) | ----- | 2500 | V |
| T _{stg} | Storage Temperature | -55 to 175 | | °C |
| T _j | Operating Junction Temperature | | | |

(•) Pulse width limited by safe operating area.

(*) Current Limited by package's thermal resistance

(1) I_{SD} \leq 16A, di/dt \leq 210A/ μ s, V_{DD} \leq V_{(BR)DSS}, T_j \leq T_{JMAX}.

(2) Starting T_j = 25 °C, I_D = 8A, V_{DD} = 30V

STP16NF06L/FP**THERMAL DATA**

| | | | TO-220 | TO-220FP | |
|----------------------------|---|-----|-------------|----------|------------|
| Rthj-case | Thermal Resistance Junction-case | Max | 3.33 | 6 | °C/W |
| Rthj-amb T _I | Thermal Resistance Junction-ambient Maximum Lead Temperature For Soldering Purpose | Max | 62.5 300 | | °C/W °C |

ELECTRICAL CHARACTERISTICS (T_{case} = 25 °C unless otherwise specified)

OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|----------------------|---|---|------|------|---------|----------|
| V _{(BR)DSS} | Drain-source Breakdown Voltage | I _D = 250 μA, V _{GS} = 0 | 60 | | | V |
| I _{DSS} | Zero Gate Voltage Drain Current (V _{GS} = 0) | V _{DS} = Max Rating V _{DS} = Max Rating T _C = 125°C | | | 1 10 | μA μA |
| I _{GSS} | Gate-body Leakage Current (V _{DS} = 0) | V _{GS} = ± 16V | | | ±100 | nA |

ON (1)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|---|------|--------------|--------------|--------|
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} = V _{GS} I _D = 250 μA | 1 | | | V |
| R _{DS(on)} | Static Drain-source On Resistance | V _{GS} = 5 V I _D = 8 A V _{GS} = 10 V I _D = 8 A | | 0.08 0.07 | 0.10 0.09 | Ω Ω |

DYNAMIC

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|--|---|---|------|-----------------|------|----------------|
| g _{fs} (*) | Forward Transconductance | V _{DS} > I _{D(on)} × R _{DS(on)max} , I _D = 8 A | | 17 | | S |
| C _{iss} C _{oss} C _{rss} | Input Capacitance Output Capacitance Reverse Transfer Capacitance | V _{DS} = 25V, f = 1 MHz, V _{GS} = 0 | | 345 72 29 | | pF pF pF |

ELECTRICAL CHARACTERISTICS (continued)

SWITCHING ON

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------|--|--|------|-------------------|------|----------------|
| $t_{d(on)}$ t_r | Turn-on Delay Time Rise Time | $V_{DD} = 30\text{ V}$ $I_D = 8\text{ A}$ $R_G = 4.7\ \Omega$ $V_{GS} = 4.5\text{ V}$ (Resistive Load, Figure 3) | | 10 37 | | ns ns |
| Q_g Q_{gs} Q_{gd} | Total Gate Charge Gate-Source Charge Gate-Drain Charge | $V_{DD} = 48\text{ V}$ $I_D = 16\text{ A}$ $V_{GS} = 5\text{ V}$ | | 7.3 2.1 3.1 | 10 | nC nC nC |

SWITCHING OFF

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------------|----------------------------------|--|------|------------|------|----------|
| $t_{d(off)}$ t_f | Turn-off Delay Time Fall Time | $V_{DD} = 30\text{ V}$ $I_D = 8\text{ A}$ $R_G = 4.7\ \Omega$, $V_{GS} = 4.5\text{ V}$ (Resistive Load, Figure 3) | | 20 12.5 | | ns ns |

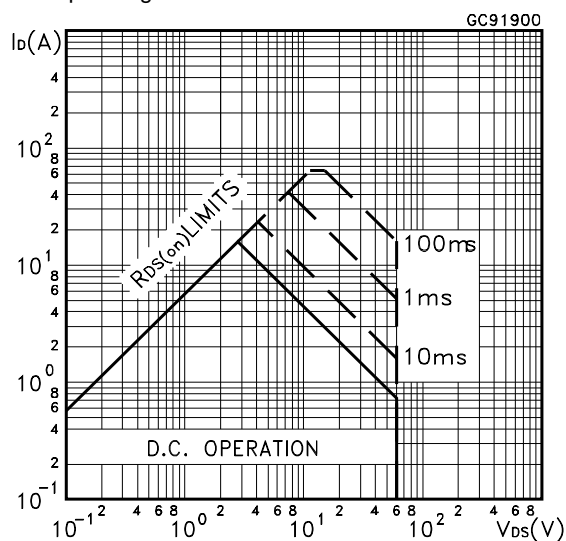
SOURCE DRAIN DIODE

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|-----------------------------------|--|---|------|-------------------|----------|---------------|
| I_{SD} $I_{SDM}^{(*)}$ | Source-drain Current Source-drain Current (pulsed) | | | | 16 64 | A A |
| $V_{SD}^{(*)}$ | Forward On Voltage | $I_{SD} = 16\text{ A}$ $V_{GS} = 0$ | | | 1.3 | V |
| t_{rr} Q_{rr} I_{RRM} | Reverse Recovery Time Reverse Recovery Charge Reverse Recovery Current | $I_{SD} = 16\text{ A}$ $di/dt = 100\text{ A}/\mu\text{s}$ $V_{DD} = 16\text{ V}$ $T_j = 150^\circ\text{C}$ (see test circuit, Figure 5) | | 50 67.5 2.7 | | ns nC A |

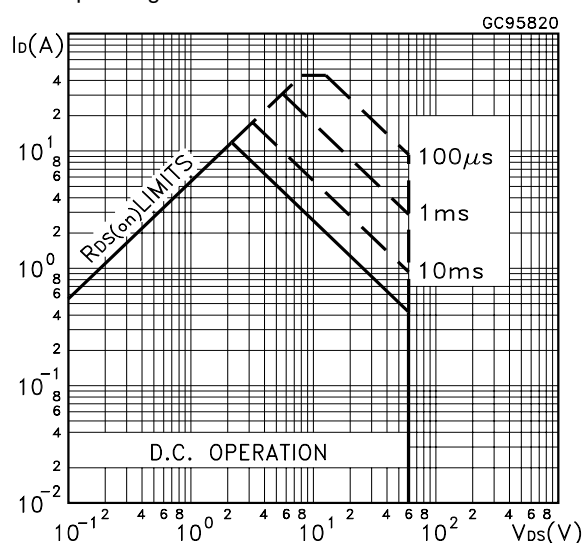
(*)Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

(●)Pulse width limited by safe operating area.

Safe Operating Area for TO-220

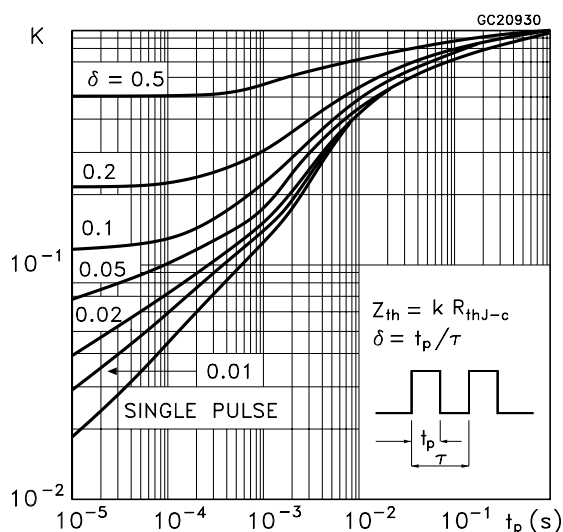


Safe Operating Area for TO-220FP

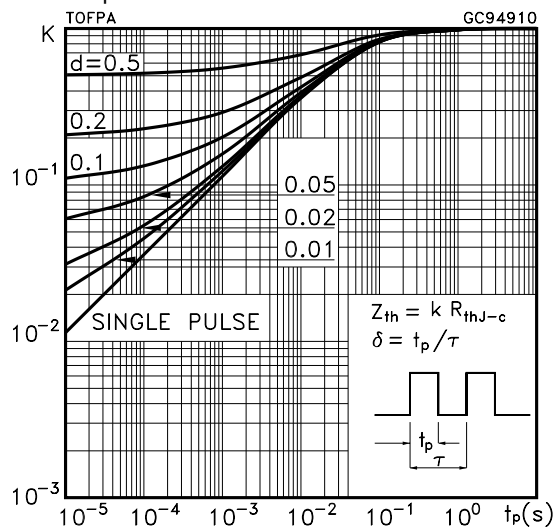


STP16NF06L/FP

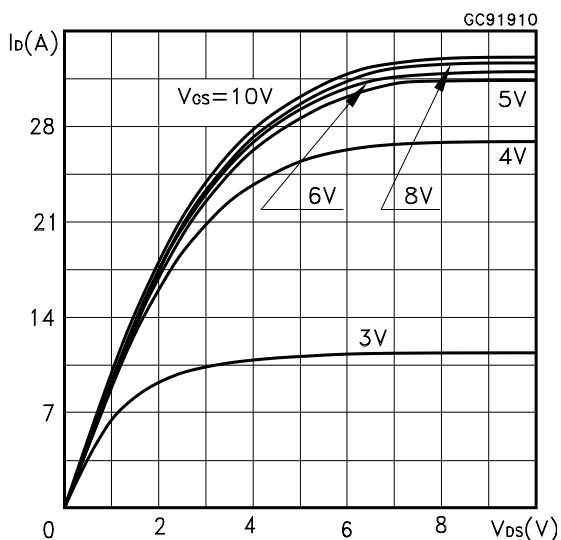
Thermal Impedance



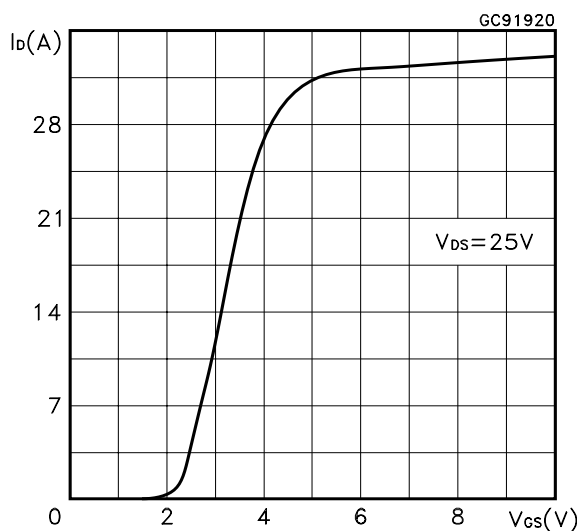
Thermal Impedance for TO-220FP



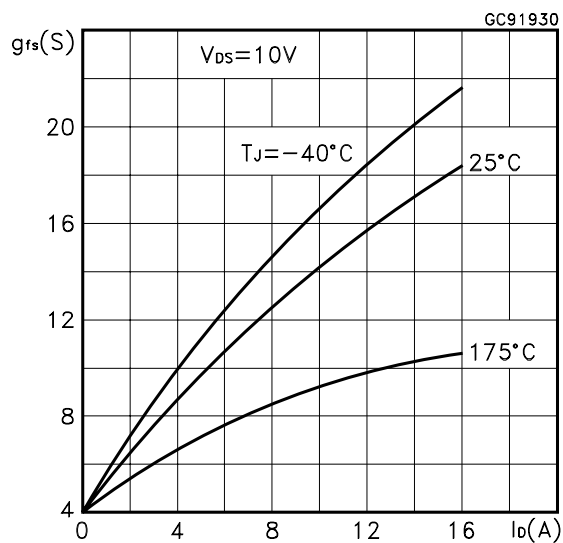
Output Characteristics



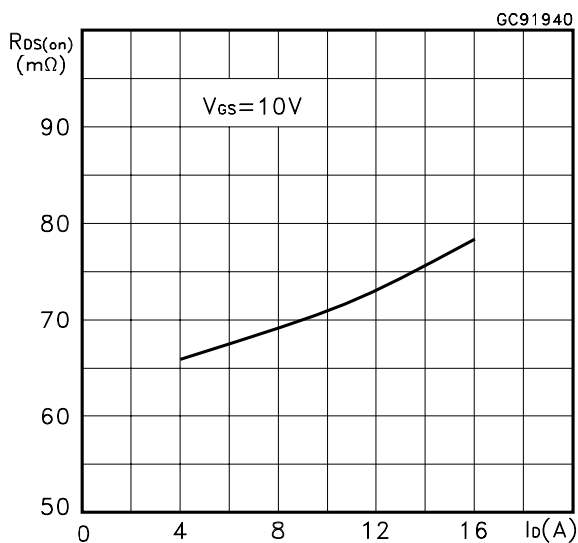
Transfer Characteristics



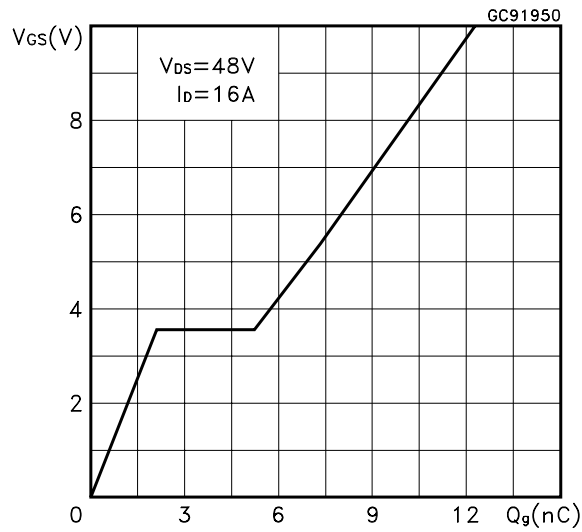
Transconductance



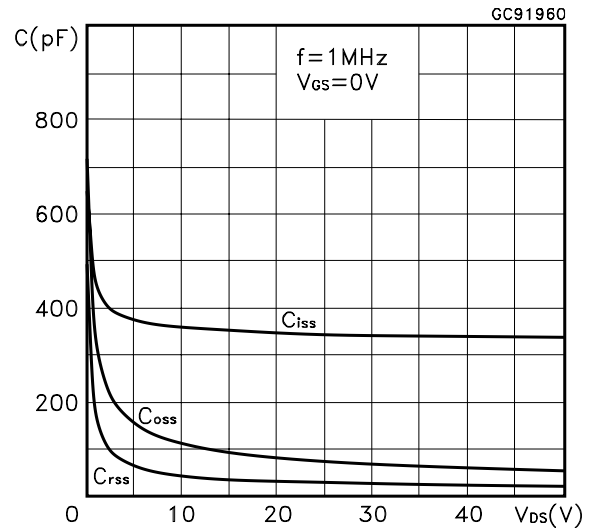
Static Drain-source On Resistance



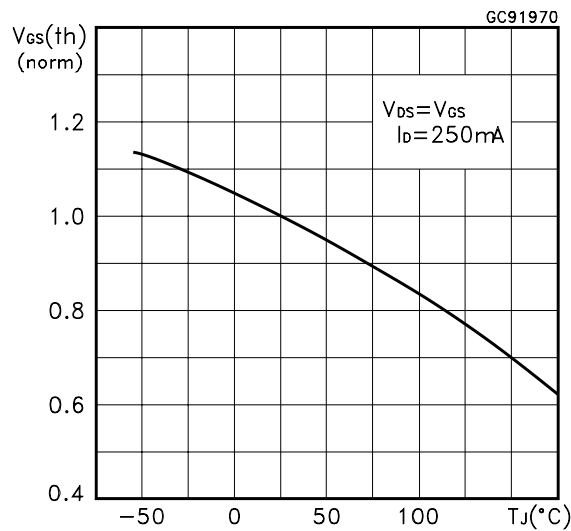
Gate Charge vs Gate-source Voltage



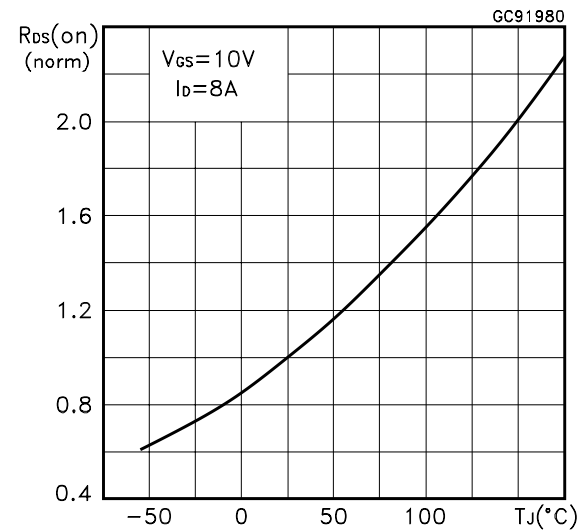
Capacitance Variations



Normalized Gate Threshold Voltage vs Temperature



Normalized on Resistance vs Temperature



Source-drain Diode Forward Characteristics

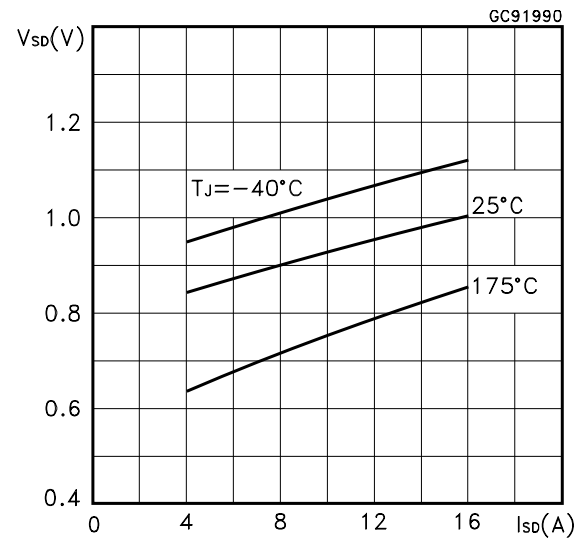


Fig. 1: Unclamped Inductive Load Test Circuit



Fig. 2: Unclamped Inductive Waveform



Fig. 3: Switching Times Test Circuits For Resistive Load



Fig. 4: Gate Charge test Circuit

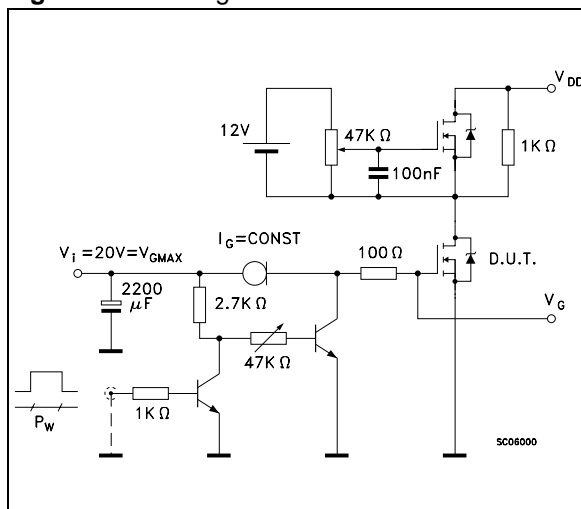
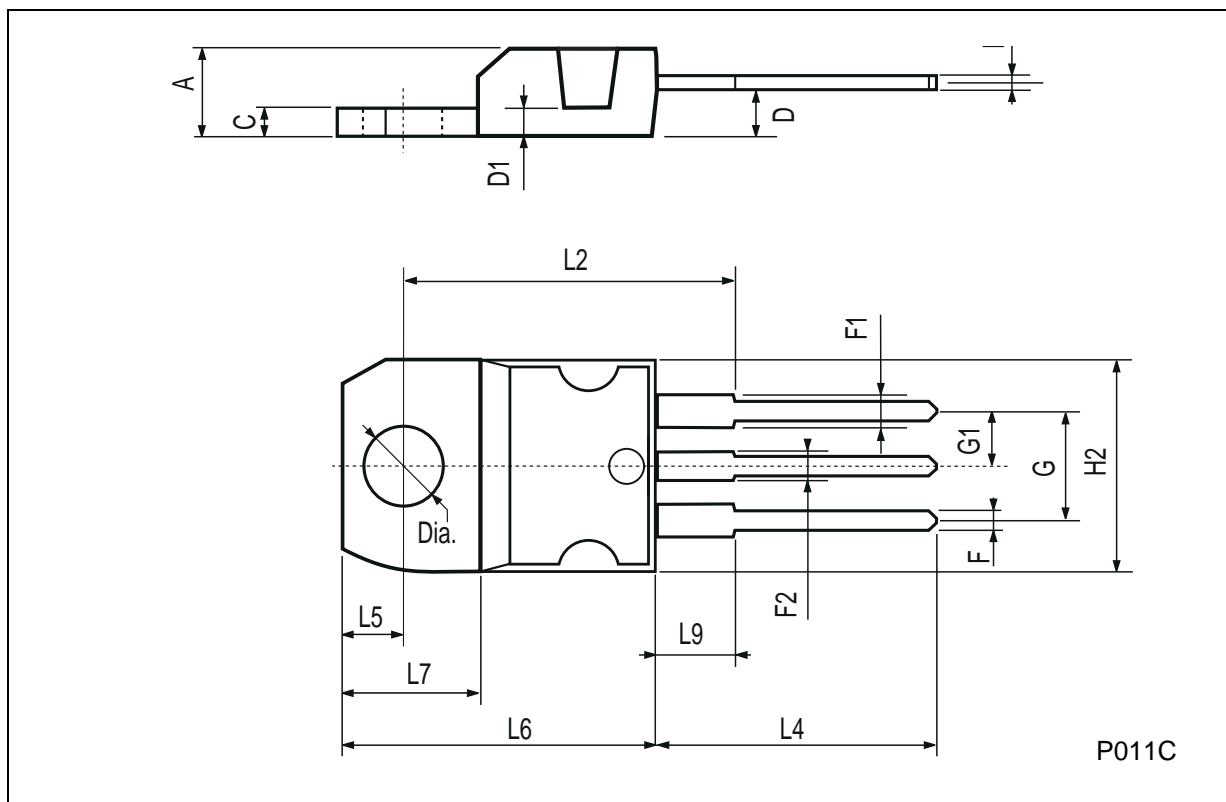


Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times



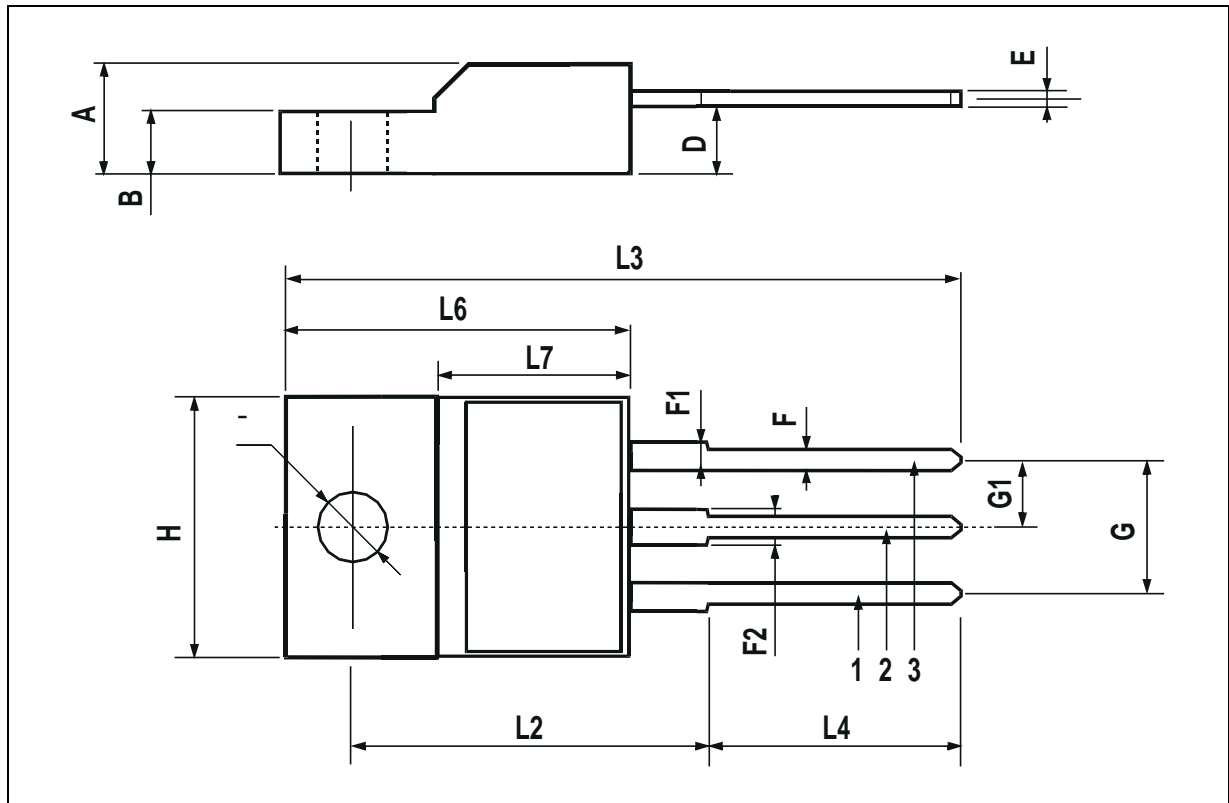
TO-220 MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|-------|------|-------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.40 | | 4.60 | 0.173 | | 0.181 |
| C | 1.23 | | 1.32 | 0.048 | | 0.051 |
| D | 2.40 | | 2.72 | 0.094 | | 0.107 |
| D1 | | 1.27 | | | 0.050 | |
| E | 0.49 | | 0.70 | 0.019 | | 0.027 |
| F | 0.61 | | 0.88 | 0.024 | | 0.034 |
| F1 | 1.14 | | 1.70 | 0.044 | | 0.067 |
| F2 | 1.14 | | 1.70 | 0.044 | | 0.067 |
| G | 4.95 | | 5.15 | 0.194 | | 0.203 |
| G1 | 2.4 | | 2.7 | 0.094 | | 0.106 |
| H2 | 10.0 | | 10.40 | 0.393 | | 0.409 |
| L2 | | 16.4 | | | 0.645 | |
| L4 | 13.0 | | 14.0 | 0.511 | | 0.551 |
| L5 | 2.65 | | 2.95 | 0.104 | | 0.116 |
| L6 | 15.25 | | 15.75 | 0.600 | | 0.620 |
| L7 | 6.2 | | 6.6 | 0.244 | | 0.260 |
| L9 | 3.5 | | 3.93 | 0.137 | | 0.154 |
| DIA. | 3.75 | | 3.85 | 0.147 | | 0.151 |



TO-220FP MECHANICAL DATA

| DIM. | mm | | | inch | | |
|------|------|------|------|-------|-------|-------|
| | MIN. | TYP. | MAX. | MIN. | TYP. | MAX. |
| A | 4.4 | | 4.6 | 0.173 | | 0.181 |
| B | 2.5 | | 2.7 | 0.098 | | 0.106 |
| D | 2.5 | | 2.75 | 0.098 | | 0.108 |
| E | 0.45 | | 0.7 | 0.017 | | 0.027 |
| F | 0.75 | | 1 | 0.030 | | 0.039 |
| F1 | 1.15 | | 1.7 | 0.045 | | 0.067 |
| F2 | 1.15 | | 1.7 | 0.045 | | 0.067 |
| G | 4.95 | | 5.2 | 0.195 | | 0.204 |
| G1 | 2.4 | | 2.7 | 0.094 | | 0.106 |
| H | 10 | | 10.4 | 0.393 | | 0.409 |
| L2 | | 16 | | | 0.630 | |
| L3 | 28.6 | | 30.6 | 1.126 | | 1.204 |
| L4 | 9.8 | | 10.6 | 0.385 | | 0.417 |
| L6 | 15.9 | | 16.4 | 0.626 | | 0.645 |
| L7 | 9 | | 9.3 | 0.354 | | 0.366 |
| Ø | 3 | | 3.2 | 0.118 | | 0.126 |



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